

Update: 20/07/2020	TECHNICAL DATA SHEET	
Ref: Alloy	Alloy	
Created on: 23/03/2007	Sn60Pb37.6Bi2.4	



GENERAL CHARACTERISTICS:

This alloy developed for soldering printed circuit boards is produced from high purity metals and specially designed to give mat solder joints.
Conform to standard ISO 9453 : alloy n° 141 and is also J-STD 006 compliant.

CHEMICAL CHARACTERISTICS:

Amount of Tin : 60 % ± 0.5%
Amount of Lead : Rest
Amount of Bismuth : 2.4% ± 0.4%
Material global purity : > 99.95%

PHYSICAL CHARACTERISTICS:

Melting point : Solidus 180°C – Liquidus 185°C
Specific weight : 8.5 g/cm³
Working temp.: solder wave machine : from 235°C to 260°C (typical)

PACKAGING / STORAGE:

Bars : Extruded Bars or Sticks in cartons of 20-25kg. Other: consult us.
Other product shape : On request
Storage : In original packaging at room temperature for 24 months.

SAFETY:

Material Safety Data Sheet available on request. Please consult it before use.

ADDITIONAL INFORMATION:

Our manufacturing processes have been subjected to FMECA analysis (equivalent of AMDEC in France).
Quality Certificate available on request.



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